

Abstract of Disclosure

500
SUB
B1
CONT.

The present invention discloses an electrostatic chucking device having a laminated structure which is formed by sequentially laminating a first insulation layer, an electrode layer and a second insulation layer on a metal substrate, wherein the first insulation layer and the second insulation layer are constituted of polyimide films, and at least the adhesion between the metal substrate and the first insulation layer, and, preferably, further, the adhesions including the adhesion between the first insulation layer and the electrode layer and the adhesion between the electrode layer and the second insulation layer are performed by using thermoplastic polyimide-based adhesive films having a film thickness of 5 to 50 μm . Further, to manufacture the electrostatic chucking devices having such a constitution, the present invention also discloses an electrostatic chucking device manufacturing method which performs the low-temperature compression bonding processing under pressure at a temperature of 100 to 250°C between the metal substrate and the first insulation layer, between the first insulation layer and the electrode layer, and between the electrode layer and the second insulation layer using thermoplastic polyimide-based adhesion films. According to the present invention, the electrostatic chucking device can exhibit the excellent attraction performance over a long period while

SUB
B1
concl'd.

ensuring the excellent durability and the excellent heat resistance. Further, the method can manufacture the electrostatic chucking devices which do not contaminate a periphery of the device and a wafer.

TOP SECRET